

LoRaWAN Modem Module Data Sheet

Sample Part Number: **CMWX1ZZABZ-TEMP-2**
MP Part Number: **CMWX1ZZABZ-093**

Revision History

Revision Code	Date	Description	Comments
A	Dec 20, 2016	Initial Draft	
B	Feb 23, 2017	Updated pin description according to MuRata LoRa modem command specification v0.5	
C	July 3, 2017	Added reference circuit	
D	Sep 29, 2017	Updated reference circuit	
E	Nov 23, 2017	Updated Electrical Characteristics and reference circuit	
F	May 14, 2018	Revised Label info	
G	July 4, 2019	Revised Label info by adding Anatel ID	
H	Feb 18, 2020	Revised Label info by adding part number	
I	Feb 23, 2021	Revised Operating Condition	
J	Apr 21, 2021	Revised Operating Condition Label Picture	
K	Sep 02, 2021	Revised Label information	
L	Oct 22, 2021	Revised Label information	
M	Mar 3, 2023	Revised Label information in page 8	JRL number
N	Sep 17, 2025	Remove the "Confidential" wording	

TABLE OF CONTENTS

1. Features	4
2. Part Number	4
3. Block Diagram	4
4. Dimensions, Marking and Terminal Configurations	5
5. Label Information	8
6. Absolute Maximum Ratings	9
7. Operating Condition	9
8. Electrical Characteristics	9
9. Power Sequences	11
10. Recommend Land Pattern	12
11. Reference circuit	13
12. Tape and Reel packing	14
13. Notice	17

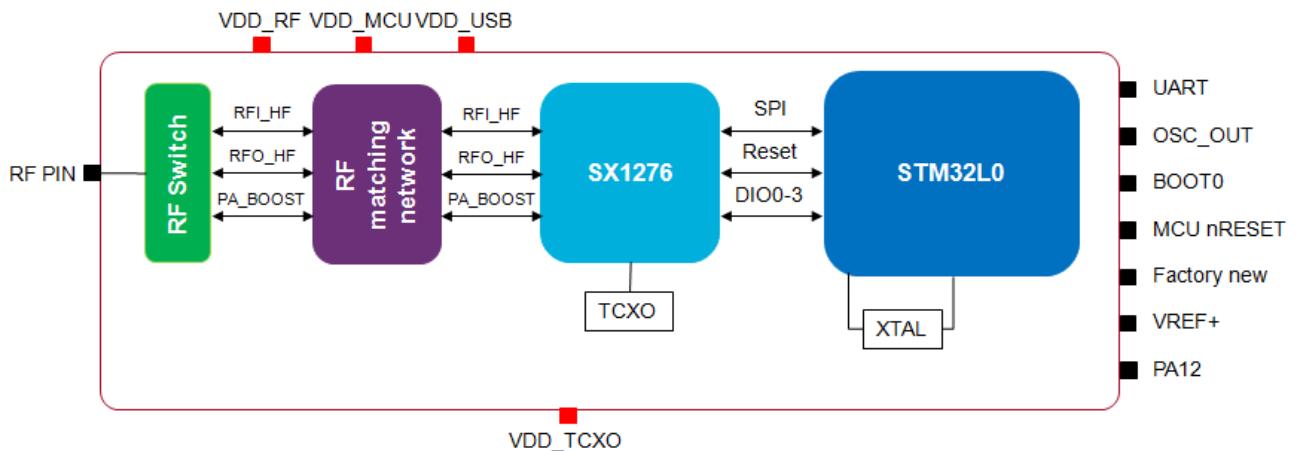
1. Features

Interfaces	: UART
Main ICs	: STM32L, SX1276
Reference Clocks	: Integrated 32MHz clock (TCXO with frequency error=±2 ppm) and 32.768KHz clock (frequency error=±20 ppm)
Supported Frequencies	: 868 MHz, 915 MHz
Module Size	: 12.5 mm x 11.6 mm x 1.76 mm (Max.)
Weight	: 0.48g (Typ.)
Package	: Metal Shield can
RoHS	: This module is compliant with the RoHS directive

2. Part Number

Ordering Part Number	Description
CMWX1ZZABZ-TEMP-2	Engineering sample
CMWX1ZZABZ-EVK-2	Evaluation board
CMWX1ZZABZ-093	MP P/N

3. Block Diagram



4. Dimensions, Marking and Terminal Configurations

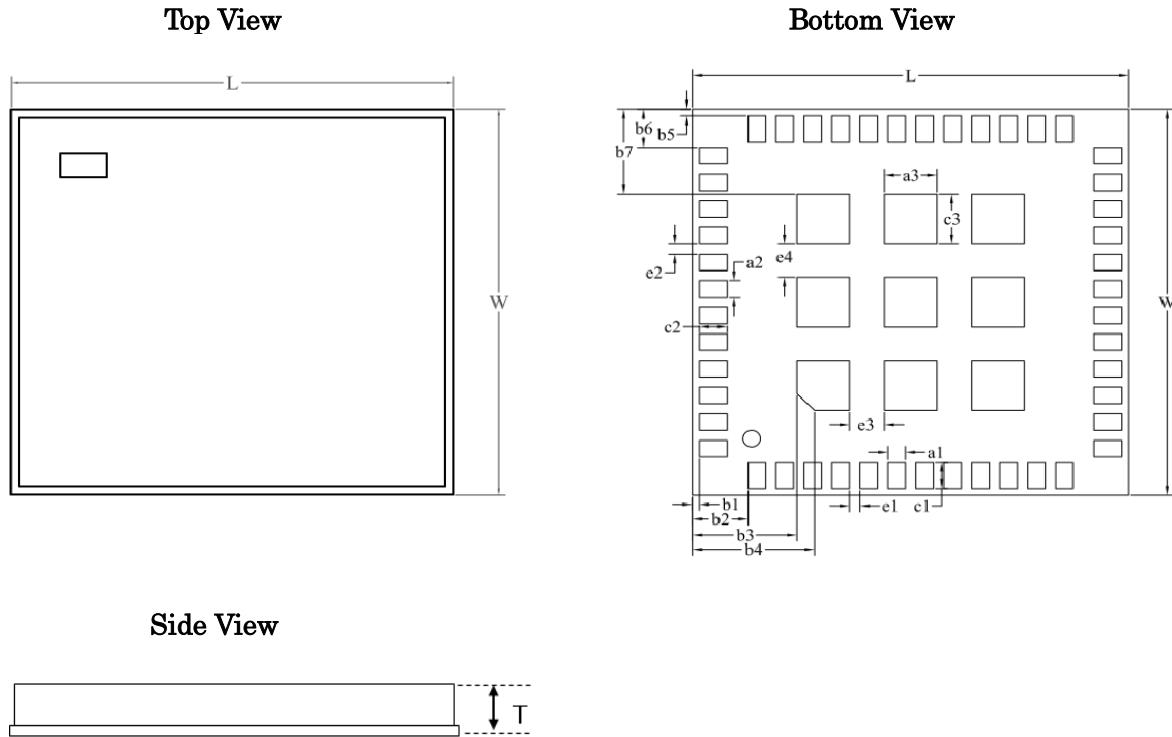


Table 1 Dimension (Unit: mm)

Mark	Dimension	Mark	Dimension	Mark	Dimension
L	12.5 ± 0.20	W	11.6 ± 0.20	T	1.76 max
a1	0.50 ± 0.10	a2	0.50 ± 0.10	a3	1.50 ± 0.10
b1	0.20 ± 0.15	b2	1.60 ± 0.15	b3	3.00 ± 0.15
b4	3.50 ± 0.15	b5	0.20 ± 0.15	b6	1.15 ± 0.15
b7	2.55 ± 0.15	c1	0.80 ± 0.10	c2	0.80 ± 0.10
c3	1.50 ± 0.10	e1	0.30 ± 0.10	e2	0.30 ± 0.10
e3	1.00 ± 0.10	e4	1.00 ± 0.10		

Terminal Configurations

< Top View >

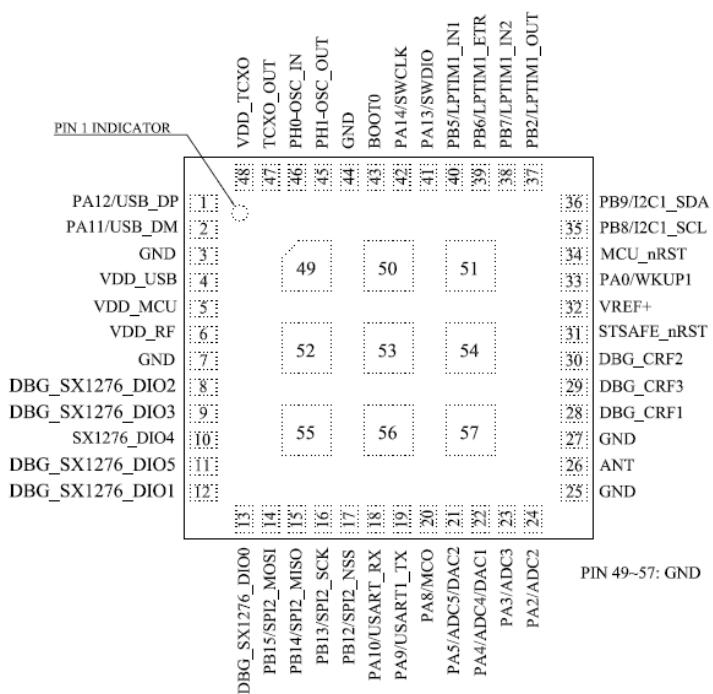


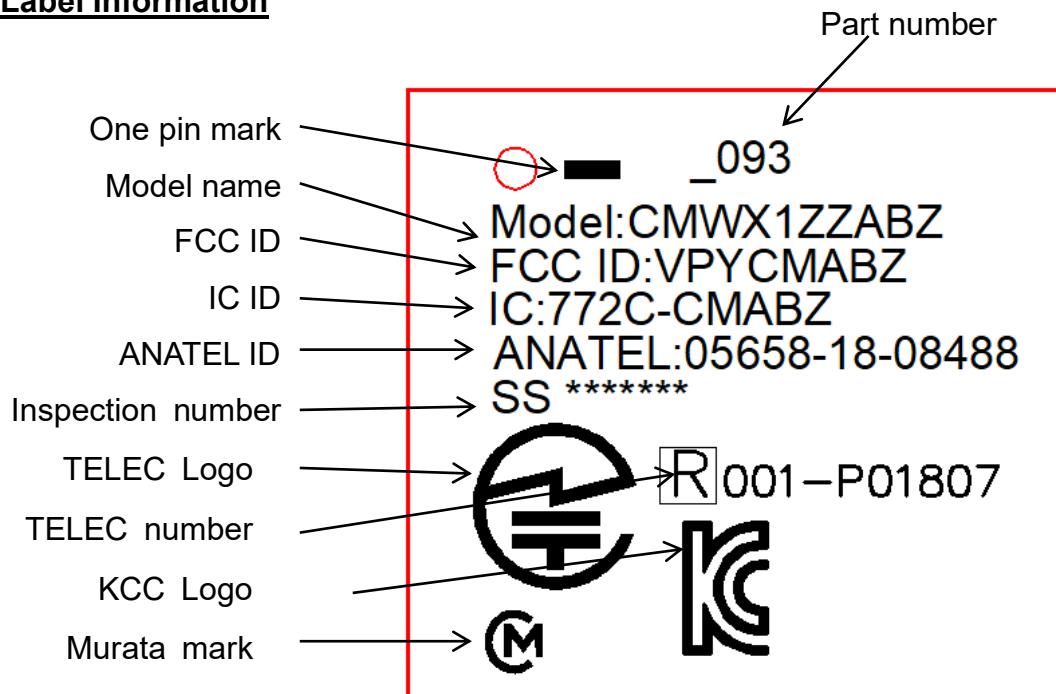
Table 2 Terminal Configurations

Pin NO.	Terminal Name	Type	Connection to IC terminal	Description
1	PA12/USB_DP	0	STM32L072_PA12	Only power supply for TCXO
2	PA11/USB_DM	I/O	STM32L072_PA11	Unused
3	GND	Ground	–	Ground
4	VDD_USB	Power	–	Power supply for PA12/PA11
5	VDD MCU	Power	–	Power supply for MCU
6	VDD_RF	Power	–	Power supply for RF IC
7	GND	Ground	–	Ground
8	DBG_SX1276_DIO2	I/O	SX1276_DIO2	Debug pin for SX1276, customer cannot use it
9	DBG_SX1276_DIO3	I/O	SX1276_DIO3	Debug pin for SX1276, customer cannot use it
10	DBG_SX1276_DIO4	I/O	SX1276_DIO4	SX1276_DIO4, customer cannot use it
11	DBG_SX1276_DIO5	I/O	SX1276_DIO5	Debug pin for SX1276, customer cannot use it
12	DBG_SX1276_DIO1	I/O	SX1276_DIO1	Debug pin for SX1276, customer cannot use it
13	DBG_SX1276_DIO0	I/O	SX1276_DIO0	Debug pin for SX1276, customer cannot use it
14	PB15/SPI2_MOSI	I	STM32L072_PB15	Input for factory new. In normal work mode, this pin should be pulled up. If this pin is pulled down continuously more than 5 seconds and then pulled up, the module will be restored to factory new.
15	PB14/SPI2_MISO	I/O	STM32L072_PB14	Unused
16	PB13/SPI2_SCK	I/O	STM32L072_PB13	Unused
17	PB12/SPI2_NSS	I/O	STM32L072_PB12	Unused
18	PA10/USART1_RX	I/O	STM32L072_PA10	Debug interface.
19	PA9/USART1_TX	I/O	STM32L072_PA9	Debug interface.
20	PA8/MCO	I/O	STM32L072_PA8	Unused
21	PA5/ADC5/DAC2	I/O	STM32L072_PA5	Unused
22	PA4/ADC4/DAC1	I/O	STM32L072_PA4	Unused
23	PA3/ADC3	I/O	STM32L072_PA3	UART_RX for AT command interface
24	PA2/ADC2	I/O	STM32L072_PA2	UART_TX for AT command interface
25	GND	Ground	–	Ground
26	ANT	A, I/O	–	Transmit / Receive antenna
27	GND	Ground	–	Ground
28	DBG_CRF1	I/O	STM32L072_PA1	Unused

29	DBG_CRF3	I/O	STM32L072_PC1	Unused
30	DBG_CRF2	I/O	STM32L072_PC2	Unused
31	STSAFE_nRST	I	–	Unused
32	VREF+	Power	–	Reference Voltage for ADC and DAC
33	PA0/WKUP1	I/O	STM32L072_PA0	Input for bootloader mode. In normal work mode, this pin should be pulled up. If this pin is pulled down during power on, the module will enter bootloader mode.
34	MCU_nRST	I	STM32L072_nRST	nRST
35	PB8/I2C1_SCL	I/O	STM32L072_PB8	Unused
36	PB9/I2C1_SDA	I/O	STM32L072_PB9	Unused
37	PB2/LPTIM1_OUT	I/O	STM32L072_PB2	Unused
38	PB7/LPTIM1_IN2	I/O	STM32L072_PB7	Unused
39	PB6/LPTIM1_ETR	I/O	STM32L072_PB6	Unused
40	PB5/LPTIM1_IN1	I/O	STM32L072_PB5	Unused
41	PA13/SWDIO	I/O	STM32L072_PA13	Unused
42	PA14/SWCLK	I/O	STM32L072_PA14	Unused
43	BOOT0	I	STM32L072_BOOT0	Boot Option
44	GND	Ground	–	Ground
45	PH1-OSC_OUT	I/O	STM32L072_PH1	Unused
46	PH0-OSC_IN	I/O	STM32L072_PH0	Unused
47	TCXO_OUT	0	–	Internal TCXO output
48	VDD_TCXO	Power	–	Power supply for the TCXO
49~57	GND	Ground	–	Ground

Notes: GPIO pins are to be left OPEN if not used.

5. Label Information



6. Absolute Maximum Ratings

Table 3 Maximum ratings

Parameters		Min	Typ	Max	Unit
Storage Temperature		-40	25	+90	degC
Input RF Level		-	-	10	dBm
Supply Voltage	VDD_USB	-0.3	-	3.9	V
	VDD MCU, VDD RF, VDD TCXO	-0.3	-	3.9	V
	VREF+	-0.3	-	$V_{DD_MCU}+0.4$	V

7. Operating Condition

Table 4 Operating specification

Parameters		Min	Typ	Max	Unit
Operating Temperature		-40	25	+85	degC
Supply Voltage	VDD_USB (USB peripheral used) ⁽¹⁾	3.0	-	3.6	V
	VDD_USB(USB peripheral not used) ⁽¹⁾	$V_{DD_MCU_min}$	V_{DD_MCU}	$V_{DD_MCU_max}$	V
	VDD MCU, VDD RF, VDD TCXO	2.2 ⁽³⁾	-	3.6	V
	VREF+ ⁽²⁾	1.8	-	V_{DD_MCU}	V

(1) VDD_USB must respect the following conditions:

- When VDD MCU is powered on ($VDD_MCU < VDD_MCU_min$), VDD_USB should be always lower than VDD MCU.
- When VDD MCU is powered down ($VDD_MCU < VDD_MCU_min$), VDD_USB should be always lower than VDD MCU.
- In operating mode, VDD_USB could be lower or higher than VDD MCU.
- If the USB is not used, VDD_USB must be tied to VDD MCU to be able to use PA11 and PA12 as standard I/Os.

(2) VREF+ is used to ensure a better accuracy on low-voltage inputs and outputs of ADC and DAC. Detailed information is on the STM32L072*** datasheet and user guider.

(3) When module is on +20dBm operation, the supply of the voltage should be set from 2.4V to 3.6V.

8. Electrical Characteristics

8.1 FSK/OOK Transceiver Specification

Conditions:

Supply voltage VDD=3.3 V, temperature = 25 °C, FXOSC = 32 MHz, FRF =868/915 MHz , 2-level FSK modulation without pre-filtering, FDA = 5 kHz, Bit Rate = 4.8 kb/s and terminated in a matched 50 Ohm impedance, shared Rx and TX path matching, unless otherwise specified.

FSK/OOK Receiver Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RFS_F_HF	LnaBoost is turned on	FDA = 5 kHz, BR = 4.8 kb/s		-117.5		dBm

FSK/OOK Transmitter Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RF_OP	RF output power in 50 ohms on RFO pin (High efficiency PA)	Programmable with steps	Max	14		dBm
			Min	-5		dBm
RF_OPH	RF output power in 50 ohms on PA_BOOST pin(Regulated PA)	Programmable with 1dB steps	Max	18.5		dBm
			Min	2		dBm
ΔRF_OPH_V	RF output power stability on PA_BOOST pin versus voltage supply.	VDD = 2.2 V to 3.6 V		+/-1		dB
ΔRF_T	RF output power stability versus temperature on PA_BOOST pin.	From T = -40 °C to +85 °C		+/-1.5		dB
IDDT	Supply current in Transmit mode with impedance matching	RFOP setting = 20 dBm, on PA_BOOST		125		mA
		RFOP setting = 17 dBm, on PA_BOOST		101		mA

	RFOP setting = 14 dBm, on RFO_HF pin	46		mA
	RFOP setting = 7 dBm, on RFO_HF pin	34		mA

8.2 LoRa Transceiver Specification

Conditions:

The table below gives the electrical specifications for the transceiver operating with LoRaTM modulation. Following conditions apply unless otherwise specified: Supply voltage = 3.3 V, Temperature = 25° C, FXOSC = 32 MHz, Error Correction Code (EC) = 4/5, Packet Error Rate (PER)= 1%, CRC on payload enabled, Payload length = 10 bytes. With matched impedances

LoRa Receiver Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
IDDR_L	Current in receiver	868 band		12.5		mA
		915 band		14.5		mA
RFS_L125_HF	RF sensitivity, Long-Range Mode, LnaBoost for Band1, using split Rx/Tx path 125 kHz bandwidth	SF = 7		-122.5		dBm
		SF = 8		-125.5		dBm
		SF = 9		-128.5		dBm
		SF = 10		-131.0		dBm
		SF = 11		-133.5		dBm
		SF = 12		-135.5		dBm
RFS_L250_HF	RF sensitivity, Long-Range Mode, LnaBoost for Band1, using split Rx/Tx path 250 kHz bandwidth	SF = 7		-119.0		dBm
		SF = 8		-122.0		dBm
		SF = 9		-125.0		dBm
		SF = 10		-127.5		dBm
		SF = 11		-130.0		dBm
		SF = 12		-133.0		dBm

LoRa Transmitter Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
IDDT_L	Supply current in transmitter mode	RFOP setting = 14 dBm		36		mA
		RFOP setting = 10 dBm		27.5		mA
IDDT_H_L	Supply current in transmitter mode	Using PA_BOOST pin RFOP setting = 20 dBm		118		mA

8.3 Low power mode current

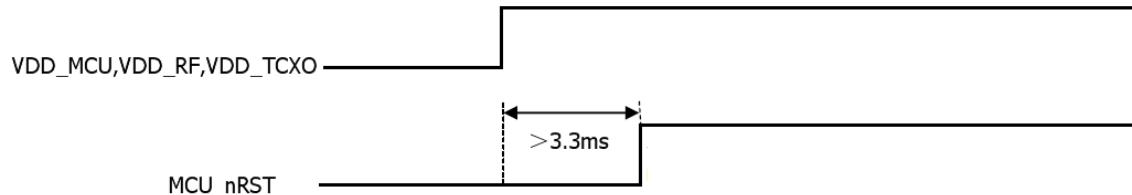
Conditions:

Power supply: 3.3V, Temp: Room,

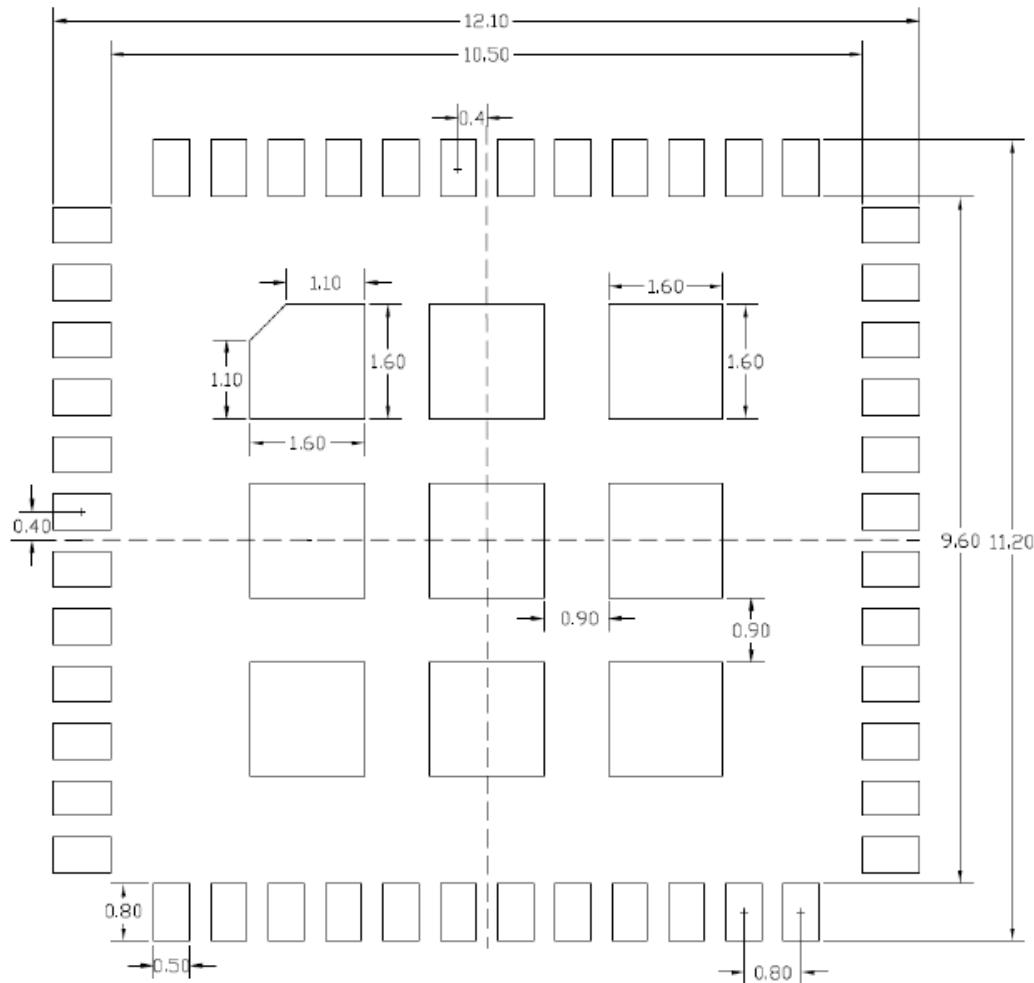
Description	Min	Typ	Max	Unit
STM32L0 in stop mode with RTC (Real Time Clock) SX1276 in sleep mode		1.65		uA

9. Power Sequences

9.1 Power Up Sequence



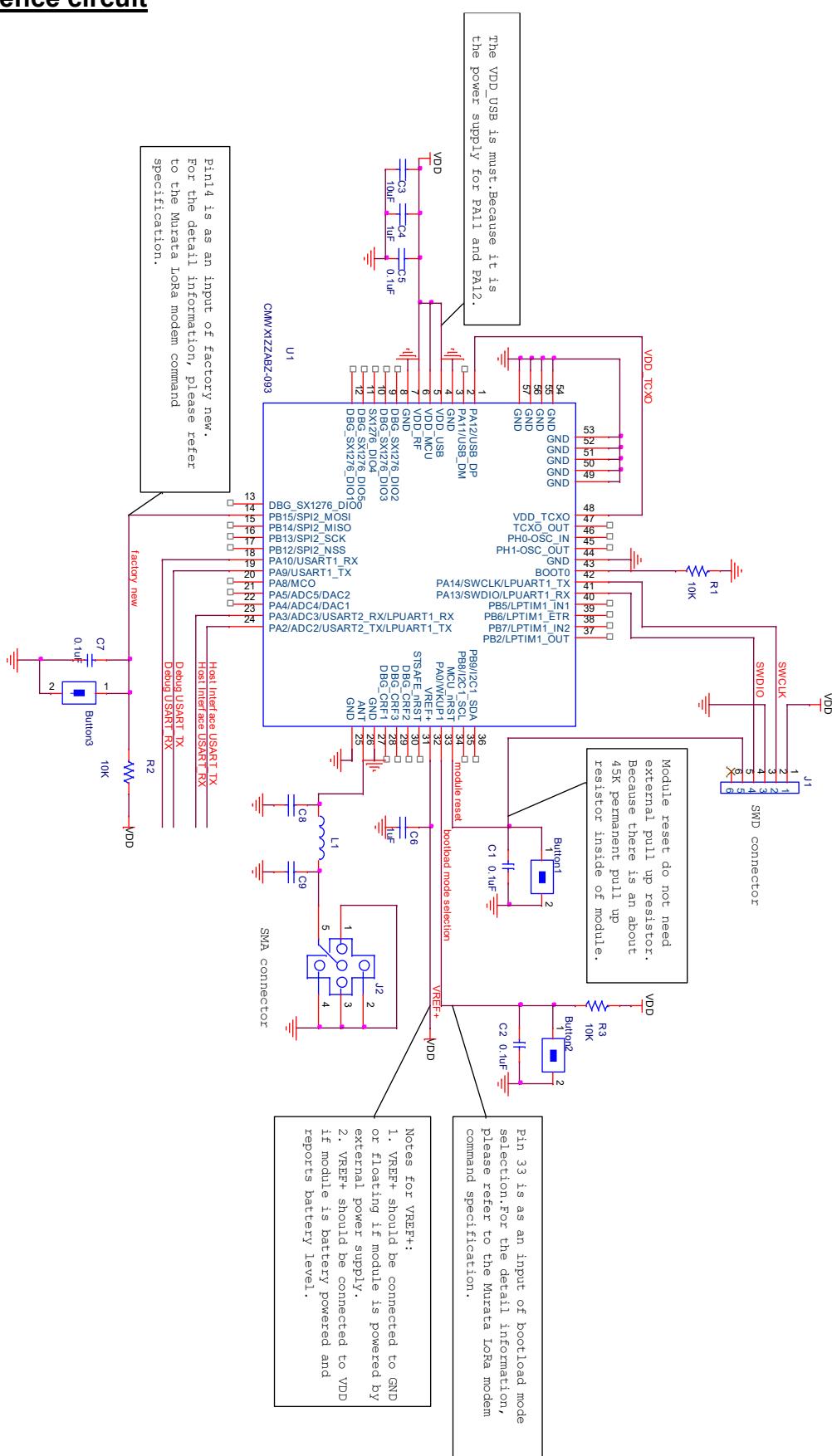
10. Recommend Land Pattern



NOTES:

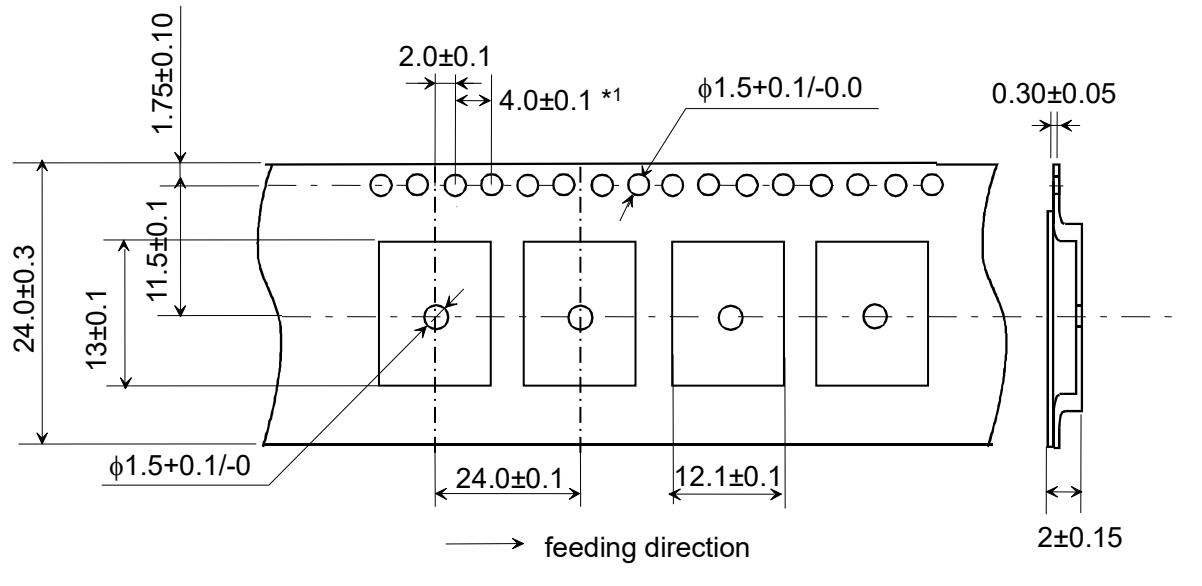
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFRENCE PURPOSE ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S
MANUFACTURING GUIDELINES ARE MET.
3. THERMAL VIAS IN THE LAND PATTERN OF THE EXPOSED PAD SHALL BE CONNECTED
TO A SYSTEM GROUND PLANE.FAILURE TO DO SO MAY COMPROMISE THE THERMAL
AND/OR FUNCTIONAL PERFORMANCE OF THE DIVICE.
4. SQUARE PACKAGE-DIMENSIOND APPLY IN BOTH "X" AND "Y" DIRECTIONS.

11. Reference circuit



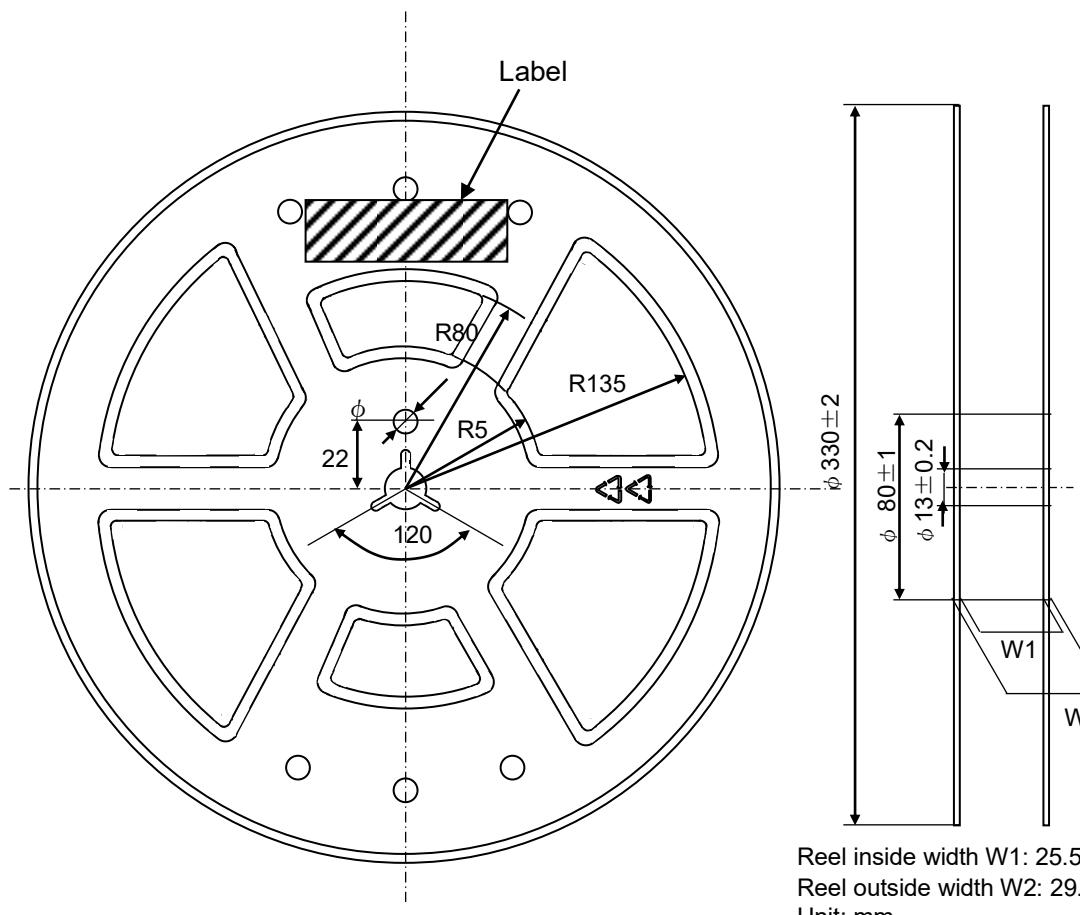
12. Tape and Reel packing

12.1 Dimension of Tape (Plastic tape)

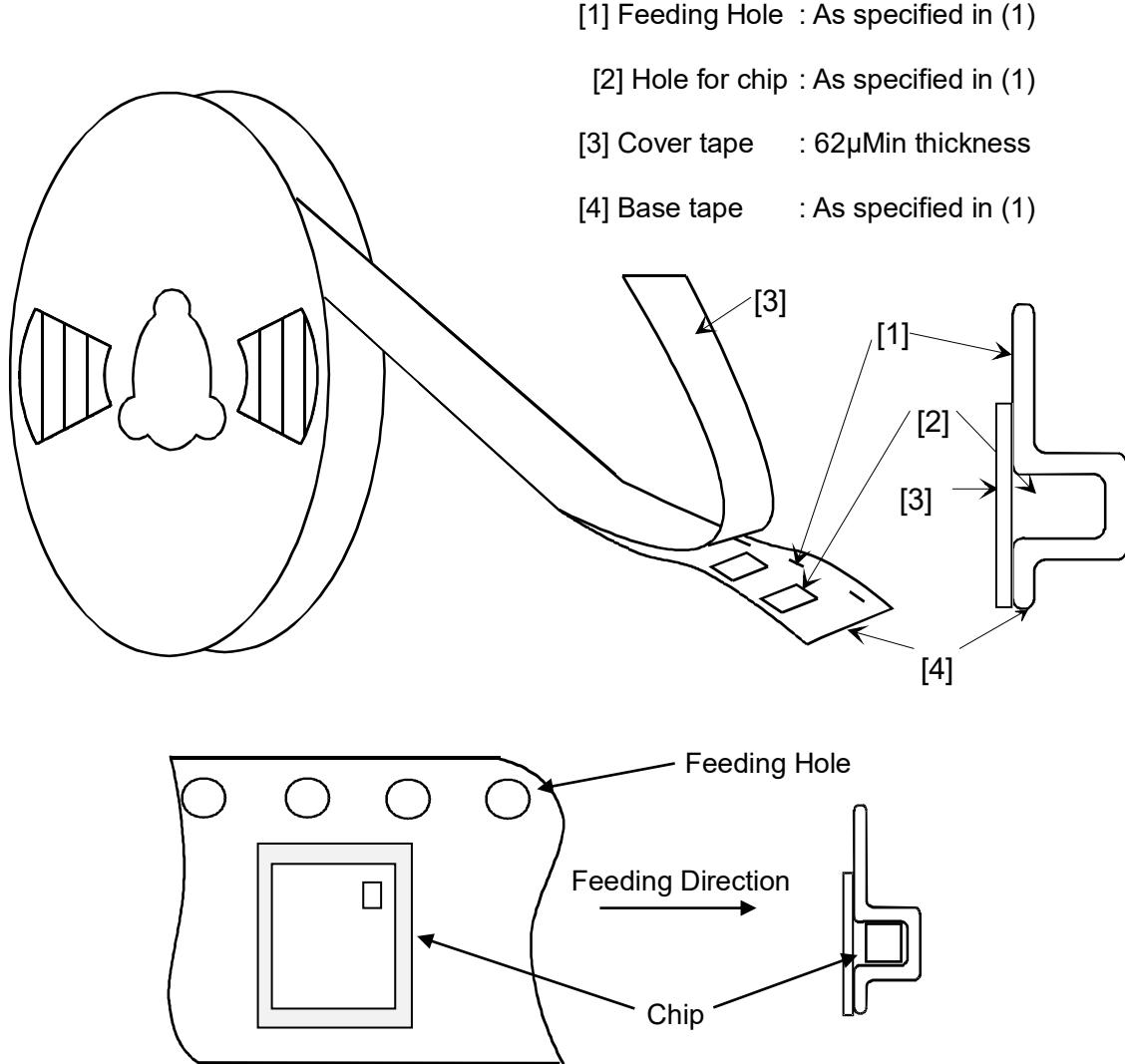


(unit : mm)

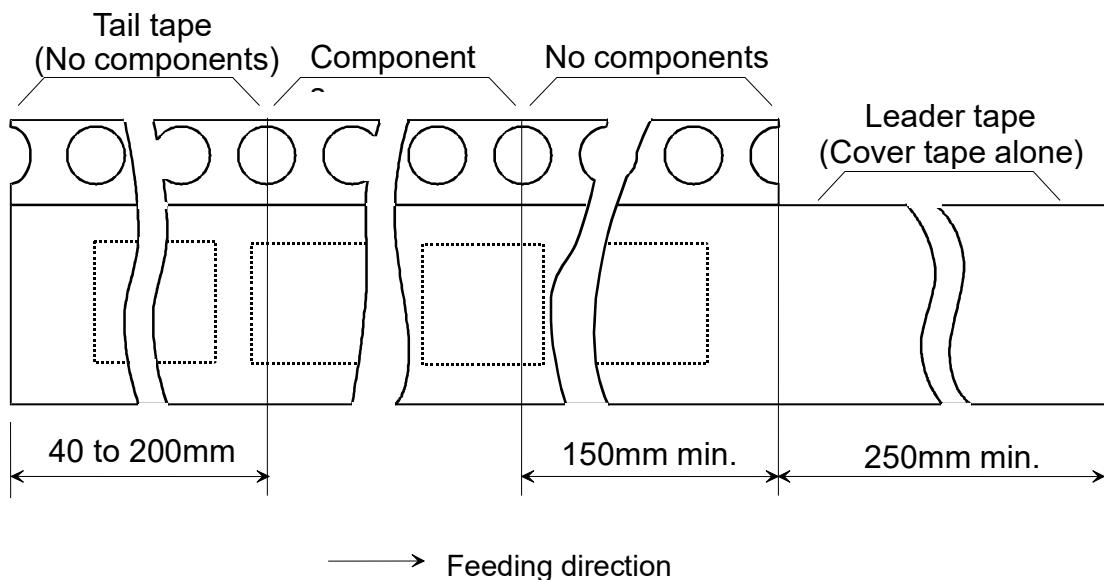
12.2 Dimensions of Reel



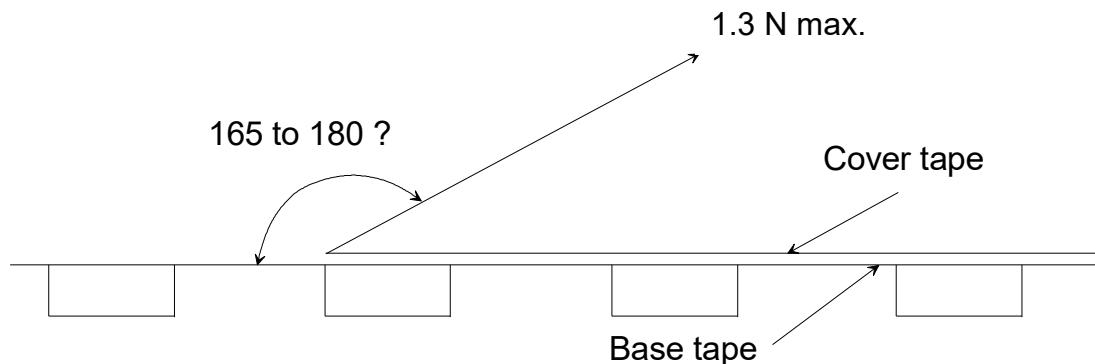
12.3 Taping Diagrams



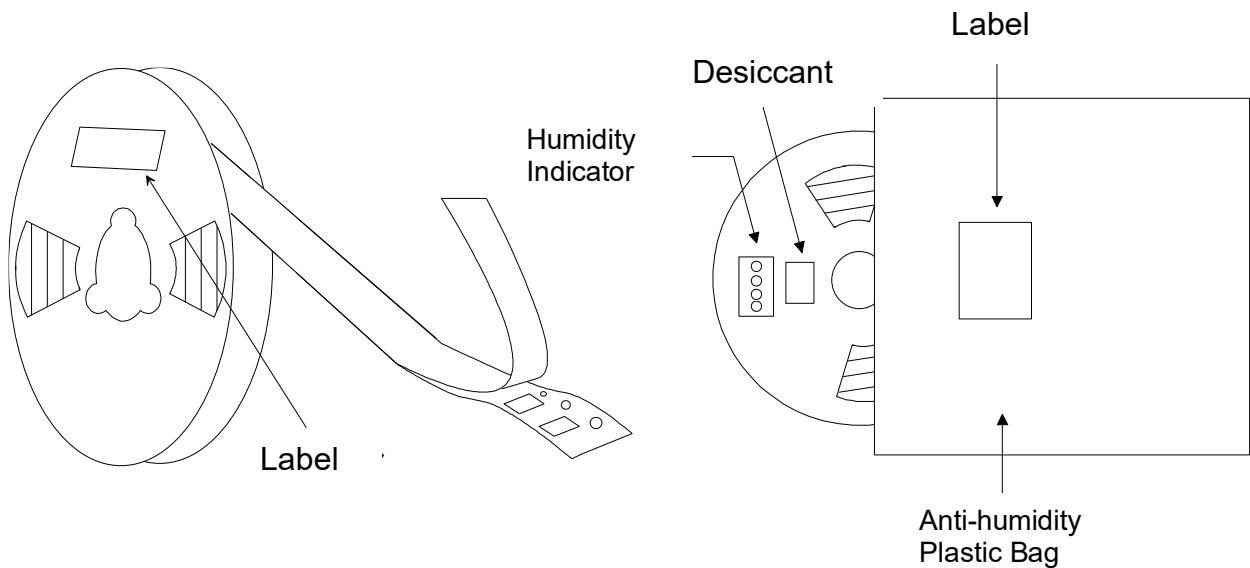
12.4 Leader and Tail tape



- The tape for chips are wound clockwise, the feeding holes to the right side as the tape is pulled toward the user.
- The cover tape and base tape are not adhered at no components area for 250mm Min.
- Tear off strength against pulling of cover tape : 5N Min.
- Packaging unit : 1000 pcs/ reel
- Material
 - Base tape : Plastic
 - Reel : Plastic
 - Cover tape, cavity tape and reel are made the anti-static processing.
- Peeling of force: 1.3N max. in the direction of peeling as shown below.



- Packaging (HumidiTyproof Packing)



Tape and reel must be sealed with the anti-humidiTyplastic bag. The bag contains the desiccant and the humidity indicator.

13. Notice

13.1 Storage Conditions

Please use this product within 6month after receipt.

- The product shall be stored without opening the packing under the ambient temperature from 5 to 35 °C and humidity from 20 ~ 70 %RH.

(Packing materials, in particular, may be deformed at the temperature over 40 °C)

- The product left more than 6months after reception, it needs to be confirmed the solderability before used.

- The product shall be stored in non corrosive gas (Cl2, NH3, SO2, Nox, etc.).

- Any excess mechanical shock including, but not limited to, sticking the packing materials by sharp object and dropping the product, shall not be applied in order not to damage the packing materials.

This product is applicable to MSL3 (Based on IPC/JEDEC J-STD-020)

- After the packing opened, the product shall be stored at <30 °C / <60 %RH and the product shall be used within 168 hours.

- When the color of the indicator in the packing changed, the product shall be baked before soldering.

Baking condition: 125 +5/-0 °C, 24 hours, 1 time

The products shall be baked on the heat-resistant tray because the material (Base Tape, Reel Tape and Cover Tape) are not heat-resistant.

13.2 Handling Conditions

Be careful in handling or transporting products because excessive stress or mechanical shock may break products.

Handle with care if products may have cracks or damages on their terminals, the characteristics of products may change. Do not touch products with bare hands that may result in poor solderability.

13.3 Standard PCB Design (Land Pattern and Dimensions)

All the ground terminals should be connected to the ground patterns. Furthermore, the ground pattern should be provided between IN and OUT terminals. Please refer to the specifications for the standard land dimensions.

The recommended land pattern and dimensions is as Murata's standard. The characteristics of products may vary depending on the pattern drawing method, grounding method, land dimensions, land forming method of the NC terminals and the PCB material and thickness. Therefore, be sure to verify the characteristics in the actual set. When using non-standard lands, contact Murata beforehand.

13.4 Notice for Chip Placer :

When placing products on the PCB, products may be stressed and broken by uneven forces from a worn-out chucking locating claw or a suction nozzle. To prevent products from damages, be sure to follow the specifications for the maintenance of the chip placer being used. For the positioning of products on the PCB, be aware that mechanical chucking may damage products.

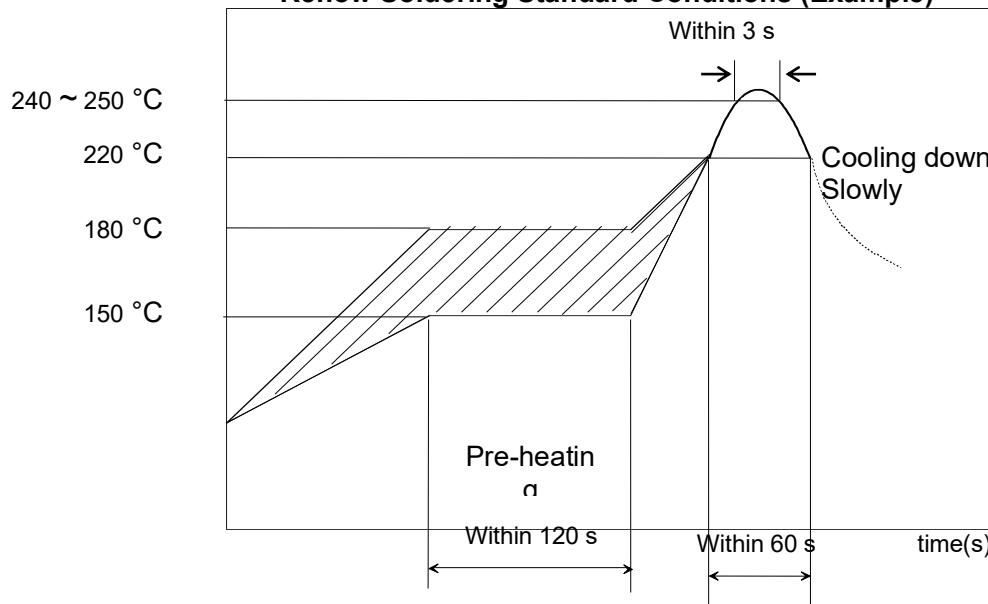
13.5 Soldering Conditions:

The recommendation conditions of soldering are as in the following figure.

When products are immersed in solvent after mounting, pay special attention to maintain the temperature difference within 100 °C. Soldering must be carried out by the above mentioned conditions to prevent products from damage. Set up the highest temperature of reflow within 260 °C.

Contact Murata before use if concerning other soldering conditions.

Reflow Soldering Standard Conditions (Example)



Please use the reflow within 2 times.

Use rosin Type flux or weakly active flux with a chlorine content of 0.2 wt % or less.

13.6 Cleaning :

Since this Product is Moisture Sensitive, any cleaning is not permitted.

13.7 Operational Environment Conditions :

Products are designed to work for electronic products under normal environmental conditions (ambient temperature, humidity and pressure). Therefore, products have no problems to be used under the similar conditions to the above-mentioned. However, if products are used under the following circumstances, it may damage products and leakage of electricity and abnormal temperature may occur.

- In an atmosphere containing corrosive gas (Cl₂, NH₃, SO_x, NO_x etc.).
- In an atmosphere containing combustible and volatile gases.
- Dusty place.
- Direct sunlight place.
- Water splashing place.
- Humid place where water condenses.
- Freezing place.

If there are possibilities for products to be used under the preceding clause, consult with Murata before actual use.

As it might be a cause of degradation or destruction to apply static electricity to products, do not apply static electricity or excessive voltage while assembling and measuring.

13.8 Input Power Capacity :

Products shall be used in the input power capacity as specified in this specifications.

Inform Murata beforehand, in case that the components are used beyond such input power capacity range.

⚠ CAUTION

PLEASE READ THIS NOTICE BEFORE USING OUR PRODUCTS.

Please make sure that your product has been evaluated and confirmed from the aspect of the fitness for the specifications of our product when our product is mounted to your product.

All the items and parameters in this product specification/datasheet/catalog have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment specified in this specification. You are requested not to use our product deviating from the condition and the environment specified in this specification.

Please note that the only warranty that we provide regarding the products is its conformance to the specifications provided herein. Accordingly, we shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification.

WE HEREBY DISCLAIMS ALL OTHER WARRANTIES REGARDING THE PRODUCTS, EXPRESS OR IMPLIED, INCLUDING WITHOUT LIMITATION ANY WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE, THAT THEY ARE DEFECT-FREE, OR AGAINST INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHTS.

The product shall not be used in any application listed below which requires especially high reliability for the prevention of such defect as may directly cause damage to the third party's life, body or property. You acknowledge and agree that, if you use our products in such applications, we will not be responsible for any failure to meet such requirements.

Furthermore, YOU AGREE TO INDEMNIFY AND DEFEND US AND OUR AFFILIATES AGAINST ALL CLAIMS, DAMAGES, COSTS, AND EXPENSES THAT MAY BE INCURRED, INCLUDING WITHOUT LIMITATION, ATTORNEY FEES AND COSTS, DUE TO THE USE OF OUR PRODUCTS IN SUCH APPLICATIONS.

- Aircraft equipment.
- Aerospace equipment
- Undersea equipment.
- Power plant control equipment
- Medical equipment.
- Transportation equipment (vehicles, trains, ships, elevator, etc.).
- Traffic signal equipment.
- Disaster prevention / crime prevention equipment.
- Burning / explosion control equipment
- Application of similar complexity and/ or reliability requirements to the applications listed in the above.

We expressly prohibit you from analyzing, breaking, Reverse-Engineering, remodeling altering, and reproducing our product. Our product cannot be used for the product which is prohibited from being manufactured, used, and sold by the regulations and laws in the world.

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Please do not use our products, our technical information and other data provided by us for the purpose of developing of mass-destruction weapons and the purpose of military use.

Moreover, you must comply with "foreign exchange and foreign trade law", the "U.S. export administration regulations", etc.

Please note that we may discontinue the manufacture of our products, due to reasons such as end of supply of materials and/or components from our suppliers.

Customer acknowledges that Murata will, if requested by you, conduct a failure analysis for defect or alleged defect of Products only at the level required for consumer grade Products, and thus such analysis may not always be available or be in accordance with your request (for example, in cases where the defect was caused by components in Products supplied to Murata from a third party).

By signing on specification sheet or approval sheet, you acknowledge that you are the legal representative for your company and that you understand and accept the validity of the contents herein. When you are not able to return the signed version of specification sheet or approval sheet within 90 days from receiving date of specification sheet or approval sheet, it shall be deemed to be your consent

on the content of specification sheet or approval sheet.

Customer acknowledges that engineering samples may deviate from specifications and may contain defects due to their development status.

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In particular we disclaim liability for damages caused by

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- deviation or lapse in function of engineering sample,
- improper use of engineering samples.

We disclaims any liability for consequential and incidental damages.

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